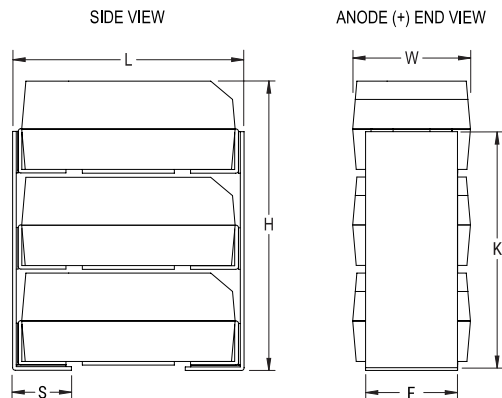


TSP, Tantalum, Polymer Tantalum, HRA, 100 uF, 20%, 50 VDC, 3X



| General Information | |
|----------------------|--|
| Series: | TSP |
| Dielectric: | Polymer Tantalum |
| Style: | Stacked Chip |
| Description: | SMD, Polymer, KO, Stacks, High Reliability |
| Features: | High Reliability |
| RoHS: | Yes |
| Termination: | Tin |
| Termination (Stack): | Silver Plated |
| AEC-Q200: | No |
| MSL: | 3 |

| Dimensions | |
|------------|------------------|
| Case Code | 3X |
| L | 8mm +/-0.38mm |
| W | 4.4mm +/-0.2mm |
| H | 13.3mm +/-0.38mm |
| S | 1.9mm +/-0.38mm |
| F | 3mm +/-0.2mm |
| K | 11mm +/-0.38mm |

| Specifications | |
|--------------------------|--------------------------------|
| Capacitance: | 100 uF |
| Capacitance Tolerance: | 20% |
| Voltage DC: | 50 VDC (105C), 33.5 VDC (125C) |
| Temperature Range: | -55/+125°C |
| Rated Temperature: | 105°C |
| Dissipation Factor: | 10% 120Hz 25C |
| Failure Rate: | N/A |
| Resistance: | 25 mOhms (100kHz 25C) |
| Leakage Current: | 500 uA (5min 25°C) |
| Testing and Reliability: | 4 Cycles At +25C +/-5C |

| Packaging Specifications | |
|--------------------------|------|
| Packaging: | Tray |
| Packaging Quantity: | 50 |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

单击下面可查看定价，库存，交付和生命周期等信息

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